Docket No.

291619US0PCT



#### PATENT AND TRADEMARK OFFICE IN THE UNI

IN RE APPLICATION OF:

Hubert MORICEAU, et al.

SERIAL NO: 10/581,111

GAU:

FILED:

May 31, 2006

**EXAMINER:** 

FOR:

METHOD FOR THE MOLECULAR BONDING OF MICROELECTRONIC COMPONENTS TO A POLYMER

FILM

# **INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.97**

COMMISSIONER FOR PATENTS ALEXANDRIA, VIRGINIA 22313

SIR:

Applicant(s) wish to disclose the following information.

### REFERENCES

- The applicant(s) wish to make of record the references listed on the attached form PTO-1449. Copies of the listed references are attached, where required, as are either statements of relevancy or any readily available English translations of pertinent portions of any non-English language references.
- ☐ A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

#### RELATED CASES

- Attached is a list of applicant's pending application(s), published application(s) or issued patent(s) which may be related to the present application. In accordance with the waiver of 37 CFR 1.98 dated September 21, 2004, copies of the cited pending applications are not provided. Cited published and/or issued patents, if any, are listed on the attached PTO form 1449.
- ☐ A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

## CERTIFICATION

- ☐ Each item of information contained in this information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this statement.
- ☐ No item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned, having made reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this statement.

## **DEPOSIT ACCOUNT**

Please charge any additional fees for the papers being filed herewith and for which no check or credit card payment is enclosed herewith, or credit any overpayment to deposit account number 15-0030. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

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APPLICANT	Form PTO 1449 U.S. DEPARTMENT OF COMMERCE (Modified) PATENT AND TRADEMARK OFFICE			ATTY DOCKET NO. 291619US0PCT		SERIAL NO. 10/581,111			
Hubert MORICEAU, et al.									
FILING DATE   May 31, 2006   May 31, 2006   May 31, 2006   U.S. PATENT DOCUMENTS									
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Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.									



U.S. PCT Application Serial No: 10/581,111

Filed: May 31, 2006

Hubert MORICEAU, et al. Docket No. 291619 US

## STATEMENT OF RELEVANCY

- 1) References AA AB & AO have been cited in the International Search Report. A copy of these references is being submitted herewith.
- 2) References have been cited in the corresponding Search Report. A copy of these references is being submitted herewith.
- 3) References AP, AW & AX are discussed in the specification. A copy of these references is being submitted herewith.
- 4) References are additional prior art known to Applicant. A copy of these references is being submitted herewith.